



Device Material Content

5555 NE Moore Ct.
Hillsboro OR 97124
custreq@latticesemi.com

Package: 132 CABGA
Total Device Weight 204.26 mg

Package Code:

BSG132

Products:

XO4

Assembly: ASEKH
Size (mm): 8 x 8
Lead pitch (mm): 0.5
MSL: 3
Reflow max (°C): 260

July, 2026

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	3.147%	6.428	3.147%	6.428	Silicon chip	7440-21-3	100.00%	Die size: 3.63 x 3.74 mm
Mold Compound	65.123%	133.019	6.770% 3.046% 50.771% 3.046% 1.354% 0.135%	13.827 6.222 103.705 6.222 2.765 0.277	Silica(Fused) 1 Silica(Fused) 2 Aluminum Oxide Epoxy resin Phenol resin Carbon Black	60676-86-0 7631-86-9 1344-28-1 Trade Secret Trade Secret 1333-86-4	10.40% 4.68% 77.96% 4.68% 2.08% 0.21%	KE-G1250AHT
D/A Epoxy	1.140%	2.328	0.981% 0.067% 0.056% 0.011% 0.021% 0.002%	2.004 0.138 0.115 0.023 0.044 0.004	Silver (Ag) 2,2-dimethyl-1,3 Propanediyl Bismethacrylate A mixture of: 4-allyl-2,6-bis(2,3-epoxypropyl)phenol Perfluoropolyoxyalkane ether xiallyoxy)methyl]butoxy)methyl]-2-ethyl-1,3-propane bis(4-tert-butylcyclohexyl) peroxydicarbonate	7440-22-4 1985-51-9 - 925918-64-5 94108-97-1 15520-11-3	86.09% 5.92% 4.92% 1.00% 1.88% 0.19%	Die attach epoxy: Henkel (Ablebond) 2100A
Wire	2.328%	4.756	2.288% 0.036% 0.004%	4.674 0.074 0.008	Copper Palladium Gold	7440-50-8 7440-05-3 7440-57-5	98.28% 1.55% 0.18%	0.7 mil diameter; 1 wire per solder ball CuPdAu+ Cu Wire (EX1P)
Solder Balls	5.352%	10.933	5.162% 0.161% 0.027% 0.003%	10.545 0.328 0.055 0.005	Tin (Sn) Silver (Ag) Copper (Cu) Nickel (Ni)	7440-31-5 7440-22-4 7440-50-8 7440-02-0	96.45% 3.00% 0.50% 0.05%	96.45SN/3.0AG/0.5CU/0.05NI_0.30MM
Substrate	14.870%	30.374	1.875% 0.739% 1.023% 1.023% 1.020% 9.192%	3.829 1.509 2.089 2.089 2.084 18.775	Continuous Filament Fiber Glass Inorganic filler Bismaleimide Triazine Epoxy Resin Other Resin Copper	65997-17-3 21645-51-2 105391-33-1 25722-66-1 9003-36-5 7440-50-8	12.61% 4.97% 6.88% 6.88% 6.86% 61.81%	BT Resin CCL-HL832NX-A
Foil	5.489%	11.212	4.641% 0.807% 0.041%	9.481 1.648 0.083	Copper Nickel Gold	7440-50-8 7440-02-0 7440-57-5	84.56% 14.70% 0.74%	
Solder Mask	2.551%	5.210	0.102% 1.173% 0.026% 0.102% 0.612% 0.536%	0.208 2.397 0.052 0.208 1.250 1.094	Morpholine derivative Barium Sulfate Silica Talc Dipropylene Glycol Monomethyl Ether Epoxy Resin	Trade secret 7727-43-7 7631-86-9 14807-96-6 34590-94-8 85954-11-6	4.00% 46.00% 1.00% 4.00% 24.00% 21.00%	Solder mask PSR4000 AUS 308

100.000%

204.260

100.000%

204.260

800.00%

Note:

Lattice regards this materials information to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Lattice subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Lattice has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Lattice products.

www.latticesemi.com



Rev. A1